CLAIMS

1. An alkali-soluble silicon-containing polymer which is represented by the general formula (1) below and has a weight-average molecular weight in the range from 500 to 500,000:

$$[A^{1}-(R^{1})_{m}-Si-O_{3/2}]_{s}[R^{2}-Si-O_{1/2}]_{t}[Si-O_{4/2}]_{u}$$
(1)

(In the formula, A^1 is a phenyl group having either a hydroxyl group or an alkoxy group; R^1 is an alkylene group of 1-4 carbons; m is 0 or 1; R^2 is an alkyl group of 1-4 carbons (R^2 in one molecule may be the same type or a combination of two or more different types.); each of s and u is a positive number; t is 0 or a positive number; $0 \le t/(s + u) \le 1$; and $0 < u/s \le 5$).

- 2. The alkali-soluble silicon-containing polymer according to Claim 1, wherein $0 \le t/(s + u) \le 0.2$ and $0.2 < u/s \le 5$ are in the general formula (1) and said polymer is solid at room temperature.
- 3. A method for manufacturing the alkali-soluble siliconcontaining polymer represented by the general formula (1) above, being characterized in performing hydrolytic co-condensation of s moles of an organosilane having a hydrolysable group represented by the general formula (2) below, t moles of an organosilane having a hydrolysable group represented by the general formula (3) below, and u moles of a silicon compound having a hydrolysable group represented by the general formula (4) below (wherein s and u are positive numbers; t is 0 or a positive number; $0 \le t/(s + u) \le 1$; and $0 < u/s \le 5$).

$$A^{1} (R^{1})_{m} Si M^{1}_{3}$$

(In the formula, A^1 is a phenyl group having either a hydroxyl group or an alkoxy group; R^1 is an alkylene group of 1-4 carbons; M^1 is a hydrolysable group; and m is 0 or 1.)

$$R^{2} = R^{2}$$

$$R^{2} - Si - M^{2}$$

$$R^{2}$$

(In the formula, R^2 is an alkyl group of 1-4 carbons; and M^2 is a hydrolysable group.)

$$SiM^3_4$$
 (4)

(In the formula, M^3 is a hydrolysable group.)

4. A silicon-containing polymer which is represented by the general formula (5) below and has a weight-average molecular weight in the range from 500 to 500,000:

$$[Si-O_{4/2}]_{w}[H-Si-O_{3/2}]_{x}[A^{2}-(R^{3})_{n}-Si-O_{3/2}]_{y}[R^{4}-Si-O_{1/2}]_{z}$$
(5)

(In the formula, A^2 is an organic group of 2-10 carbons, having a carbon-carbon unsaturated group; R^3 is an alkylene group of 1-20 carbons, a bivalent aromatic group of 6-20 carbons, or a bivalent alicyclic group of 3-20 carbons; n is 0 or 1; R^4 is a hydrogen atom or an alkyl group of 1-10 carbons (R^4 in one molecule may be the same type or a combination of two or more different types.); each of x and y is a positive number; each of w and z is 0 or a positive number; $0 \le z/(w + x + y) \le 2$; and $0.01 \le y/(w + x) \le 5$).

- 5. A heat-resistant resin composition comprising a hydrosilylated polymer obtained by a reaction between a hydrogen atom bonded to a silicon atom in the silicon-containing polymer according to Claim 4, and a carbon-carbon unsaturated group in another silicon-containing polymer according to Claim 4.
- 6. The heat-resistant resin composition according to Claim 5, having a weight loss rate of 5% or less when heated from 25°C to 1,000°C at a rate of temperature increase of 10°C/minute in nitrogen atmosphere.
- 7. A heat-resistant film, which is obtained by spreading an organic solvent solution of the silicon-containing polymer according to Claim 4 on a substrate and curing the coated film by thermal hydrosilylation.